



The drawing illustrates the mechanical specifications of the 28-pin DIP package. The top view shows a rectangular body with a central "HEAT SLUG ON BOTTOM". The pin pitch is 0.100 inches (BSC), with a total pin width of 1.37 inches (BSC). The package width is 0.75 inches (BSC), and the total height is 0.40 inches (BSC). The side view shows a maximum height of 0.35 inches (BSC) and a base thickness of 0.01 inches (BSC). The detail view shows the pin profile with a 0.015 inch (BSC) thickness and a 0.010 inch (BSC) base. The package is marked with "28" and "15" on the top, "14" and "1" on the bottom, and "PIN 1" on the left.

COMPLIANT TO JEDEC STANDARDS MS-013-AE